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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/787,380	02/26/2004	Brad L. Grande	2-I	4270
47386	7590	08/05/2009	EXAMINER	
RYAN, MASON & LEWIS, LLP			GETACHEW, ABIY	
1300 POST ROAD			ART UNIT	PAPER NUMBER
SUITE 205				2841
FAIRFIELD, CT 06824				
			MAIL DATE	DELIVERY MODE
			08/05/2009	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No. 10/787,380	Applicant(s) GRANDE ET AL.
	Examiner ABIY GETACHEW	Art Unit 2841

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED. (35 U.S.C. § 133).

Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 01 May 2009.
 2a) This action is FINAL. 2b) This action is non-final.
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 1-20 is/are pending in the application.
 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
 5) Claim(s) _____ is/are allowed.
 6) Claim(s) 1-20 is/are rejected.
 7) Claim(s) _____ is/are objected to.
 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.
 10) The drawing(s) filed on 26 February 2004 is/are: a) accepted or b) objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) Notice of References Cited (PTO-892)
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
 3) Information Disclosure Statement(s) (PTO-166/08)
 Paper No(s)/Mail Date _____

4) Interview Summary (PTO-413)
 Paper No(s)/Mail Date _____
 5) Notice of Informal Patent Application
 6) Other: _____

DETAILED ACTION

Claim Rejections - 35 USC § 103

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

2. The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.
3. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
4. Claims 1-7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Arnett et al. (US 6,078,661) hereafter refer as Arnett in view of Potters et al. (US 6,320,252) hereafter refer as Potters.

Regarding claim 1, Arnett disclose a modem module (See figure 2 element 10) for connecting to a carrier assembly (Column 2 lines 57-67), comprising: circuitry for

interfacing with a telephone line (figure 2 element 25, wire modular connectors for phone lines).

Arnett does not expressly disclose one or more solder pads for connecting a signal line of said modem module to said carrier assembly.

Potters disclose a metal panel (figure 9 element 103) having a plurality of tabs (figure 10 element 109) with barbs extending therefrom (figure 9) being mounted on a plastic frame member using an ultrasonic method.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use the method and shield design of Potters to attach the signal line of Arnett for the purpose of securing the shield on the card.

Regarding claim 2, as modified above Arnett disclose a tip/ring (figure 2 elements 28-30) connector for interfacing with said telephone line (figure 2 element 25).

Regarding claim 3, as modified above Arnett disclose a connection to a tip/ring connector (figure 2, element 28-30). (See figure 2 furthermore column 5 lines 5-6).

Regarding claim 4, as modified above Arnett disclose wherein said carrier assembly is a motherboard (see figure 2 element 22, i.e. motherboard is the central or primary circuit board making up a complex electronic system, such as a modem computer).

Regarding claim 5, as modified above Arnett disclose wherein said one or more solder pads are soldered to corresponding one or more solder pads (See figure 2 element 45) on said carrier assembly (figure 2 element 28-30).

Regarding claim 6, as modified above Arnett disclose wherein said modem

assembly is fabricated on a printed circuit board (see figure 2 element 22, i.e. motherboard is the central or primary circuit board making up a complex electronic system, such as a modern computer).

Regarding claim 7, as modified above Arnett disclose wherein said modem assembly is an integrated device (See the Abstract, i.e. a network interface device includes a circuit board secured in the base, Integrated device defined as an electronic circuit-consisting of components and connectors-contained on a semiconductor chip).

5. Claims 8-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hatam-Tabrizi et al. (2005/0093818 A1) hereafter refer as Hatam-Tabrizi in view Arnett et al. (US 6,078,661) hereafter refer as Arnett.

Regarding claims 8 and 14, Hatam-Tabrizi discloses a method for fabricating a modem module for connection to a carrier assembly (figure 2), comprising the steps of: providing circuitry on a printed circuit board (figure 2 element 17) for interfacing with a telephone line; and providing one or more solder pads (figure 2 elements 72a and 72b) on said printed circuit board (figure 2 element 17) for connecting a signal line of said modem module to said carrier assembly. (See figure 2, furthermore Page 4 column 0051 and page 6 section 0061).

Hatam-Tabrizi does not expressly disclose a telephone line.

Arnett connector for interfacing with said telephone line (figure 2 element 25).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify the circuit board as taught by Hatam-Tabrizi by having a single standard telephone line as taught by Arnett in order to provide more direct

communication and establishes connection between the input and output line terminations via traces in the circuit board.

Regarding claim 9, as modified above Arnett disclose a tip/ring (figure 2 element 28-30) connector for interfacing with said telephone line (figure 2 element 25).

Regarding claim 10, as modified above Arnett disclose a connection to a tip/ring connector (figure 2, element 28-30). (See figure 2).

Regarding claim 11, as modified above Arnett disclose wherein said carrier assembly is a motherboard (see figure 2 element 22, i.e. motherboard is the central or primary circuit board making up a complex electronic system, such as a modern computer).

Regarding claim 12, as modified above Arnett disclose wherein said one or more solder pads are soldered to corresponding one or more solder pads (See figure 2 element 45) on said carrier assembly (figure 2 element 28-30).

Regarding claim 13, as modified above Arnett disclose wherein said modem assembly is fabricated on a printed circuit board (see figure 2 element 22, i.e. motherboard is the central or primary circuit board making up a complex electronic system, such as a modern computer).

Regarding claim 15, as modified above Arnett disclose a tip/ring (figure 2 element 28-30) connector for interfacing with said telephone line (figure 2 element 25).

Regarding claim 16, as modified above Arnett disclose a connection to a tip/ring connector (figure 2, element 28-30). (See figure 2).

Regarding claim 17, as modified above Arnett disclose wherein said carrier

assembly is a motherboard (see figure 2 element 22, i.e. motherboard is the central or primary circuit board making up a complex electronic system, such as a modern computer).

Regarding claim 18, as modified above Arnett disclose wherein said one or more solder pads are soldered to corresponding one or more solder pads (See figure 2 element 45) on said carrier assembly (figure 2 element 28-30).

Regarding claim 19, as modified above Arnett disclose wherein said modem assembly is fabricated on a printed circuit board (see figure 2 element 22, i.e. motherboard is the central or primary circuit board making up a complex electronic system, such as a modern computer).

Regarding claim 20, as modified above Arnett disclose wherein said modem assembly is an integrated device. (Figure 2 element 28-30, wire modular connectors for phone lines, also known as registered jacks).

Response to Arguments

6. Applicant's arguments with respect to claims 1-20 have been considered but are moot in view of the new ground(s) of rejection.

Pertinent Art

7. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

- Fun et al. (US 6,166,913);
- Seeley et al. (US 6,370,028);
- Onoda (US 5,923,026).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to ABIY GETACHEW whose telephone number is (571)272-6932. The examiner can normally be reached on Monday to Friday 8Am to 4:30Pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, DEAN REICHARD can be reached on (571)272-1984. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Dean A. Reichard/
Supervisory Patent Examiner, Art Unit 2841

A.G.
July 31, 2009

Abiy Getachew
Examiner
Art Unit 2841